PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3540167

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DIGH HISAMOTO	08/03/2015
KEISUKE KOBAYASHI	08/04/2015
NAOKI TEGA	08/04/2015
TOSHIYUKI OHNO	07/17/2015
HIROTAKA HAMAMURA	07/21/2015
MIEKO MATSUMURA	07/21/2015

RECEIVING PARTY DATA

Name:	HITACHI, LTD.
Street Address:	6-6, MARUNOUCHI 1-CHOME, CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	100-8280

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14778058

CORRESPONDENCE DATA

Fax Number: (703)610-8686

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 7039039000
Email: tpurifoy@milesstockbridge.com, ipdocketing@milesstockbridge.com
Correspondent Name: MITCHELL W. SHAPIRO
Address Line 1: MILES & STOCKBRIDGE P.C.
Address Line 2: 1751 PINNACLE DRIVE, SUITE 1500
Address Line 4: TYSONS CORNER, VIRGINIA 22102-3833

ATTORNEY DOCKET NUMBER:	XA-12943/T3381-21798US01
NAME OF SUBMITTER:	TYNISHA PURIFOY
SIGNATURE:	/Tynisha Purifoy/
DATE SIGNED:	09/24/2015

Total Attachments: 6
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ASSIGNMENT
（譲渡証）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD.,
a corporation organized under the laws of Japan,
located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan,
receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD.,
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SILICON CARBIDE SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said HITACHI, LTD.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	(Digh HISAMOTO)	August 3, 2015
2)	(Keisuke KOBAYASHI)	
3)	(Naoki TEGA)	
4)	(Toshiyuki OHNO)	
5)	(Hirotaka HAMAMURA)	
6)	(Mieko MATSUMURA)	
7)		
8)		

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1)	(Digh HISAMOTO)	
2)	Keisuke Kobayashi (Keisuke KOBAYASHI)	August 4, 2015
3)	(Naoki TEGA)	
4)	(Toshiyuki OHNO)	
5)	(Hirotaka HAMAMURA)	
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1)	(Digh HISAMOTO)	
2)	(Keisuke KOBAYASHI)	
3)	Naoki Tega (Naoki TEGA)	August 4, 2015
4)	(Toshiyuki OHNO)	
5)	(Hirotaka HAMAMURA)	
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1)	(Digh HISAMOTO)	
2)	(Keisuke KOBAYASHI)	
3)	(Naoki TEGA)	
4)	Toshiyuki Ohno (Toshiyuki OHNO)	July 17, 2015
5)	(Hirotaka HAMAMURA)	
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4)	(Toshiyuki OHNO)	
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6)	Mieko Matsumura (Mieko MATSUMURA)	July 21, 2015
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